SPECIFICATION

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SPEC. NO.: PS-50620-XXXXX-XXX **REVISION:** B

PRODUCT NAME: 0.5/1.0mm Pitch NON-ZIF FPC Conn. SMT R/A D/C Type

PRODUCT NO: 50620 50636 50676 50678 50679 51520 Series

PREPARED:	CHECKED:	APPROVED:
Andrew	WGCH	Jason Chen
DATE: 2010.09.16	DATE: 2010.09.16	DATE: 2010.09.18

1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
O	ECN-0812063	NEW SPEC	Ryan	2008.11.10
A	ECN-0906034	ADD 50676 50678 50679 Series	Huamin	2009.06.04
B	ECN-1009111	ADD 51520 Series	Andrew	2010.09.18

2 SCOPE

This specification covers performance, tests and quality requirements for 0.5mm Pitch NON-ZIF FPC Connector. These connectors are used to hold graphic card in DSC.

Aces's P/N ： 50636-XXXXX-XXX
50620-XXXXX-XXX ; 51520-XXXXX-XXX
50676-XXXXX-XXX
50678-XXXXX-XXX
50679-XXXXX-XXX

3 APPLICABLE DOCUMENTS

EIA-364 **ELECTRONICS INDUSTRIES ASSOCIATION**

4 REQUIREMENTS

4.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

4.2.1 Contact: High performance copper alloy.
Finish: Plating pls. See the product drawing.
4.2.2 Housing: Thermoplastic High Temp., UL94V-0
4.2.3 Nut or Ear: Copper Alloy, Plating pls. See the product drawing.

4.3 Ratings

4.3.1 Voltage: 50 Volts AC (per pin)
4.3.2 Current: 0.5 Amperes (per pin)
4.3.3 Operating Temperature : -40℃ to +85℃

5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.
ELECTRICAL		
Item	**Requirement**	**Standard**
Low Level Contact Resistance	55 m Ω Max.(initial)per contact 20 m Ω Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)
Insulation Resistance	50 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	250 VAC Min. at sea level for 1 minute, Test between adjacent contacts of unmated connectors. (EIA-364-20)
Temperature rise	30℃ Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25℃ (EIA-364-70,METHOD1,CONDITION1)
MECHANICAL		
Item	**Requirement**	**Standard**
Durability	20 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)
Contact Retention Force	0.15 kgf Min.	Operation Speed： 25.4 ± 3 mm/minute. Measure the contact retention force with Tensile strength tester.
FPC Insertion/Withdrawal Force	Refer to FPC Insertion/ withdrawal force	Insert the FPC, pull the FPC at the speed rate of 25.4 ± 3 mm/min. See 8. FPC Retention Force.
Fitting Nail /Housing Retention Force	0.15 kgf MIN.	Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the fitting nail assembled in the housing.

Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)

ENVIRONMENTAL

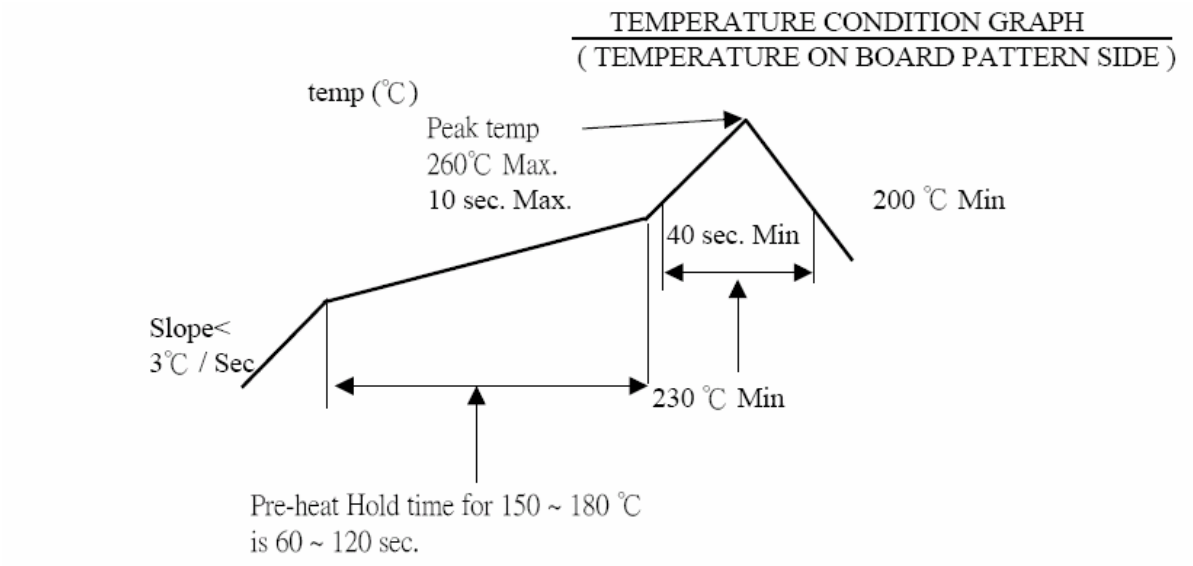
Item	Requirement	Standard
Resistance to **Reflow** Soldering Heat	See Product Qualification and Test Sequence Group 9 **(Lead Free)**	Pre Heat：150℃~180℃, 60~90sec. Heat：230℃ Min., 40sec Min. Peak Temp.： 260℃Max, 10sec Max. See 6.1 Lead free process
Thermal Shock	See Product Qualification and Test Sequence Group 3	Mate module and subject to follow condition for 5 cycles. 1 cycles: -40 +0/-3 ℃, 30 minutes +85 +3/-0 ℃, 30 minutes (EIA-364-32, test condition A)
Humidity	See Product Qualification and Test Sequence Group 3	Mated Connector 40℃, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature life	See Product Qualification and Test Sequence Group 4	Subject mated connectors to temperature life at 85℃ for 96 hours. (EIA-364-17, Test condition A)

Salt Spray	See Product Qualification and Test Sequence Group 5	Subject mated/unmated connectors to 5% salt-solution concentration, 35℃ for 8 hours. (EIA-364-26,Test condition B)
Solder ability	Solder able area shall have minimum of 95% solder coverage.	Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at 245 ±5℃, for 4-5 sec. (EIA-364-52)
Hand Soldering	Hand Soldering temperature: 350±5℃ (base on MIL-STD-202, method 208)	Contact Resistance: 40 mohms max.

Note. Flowing Mixed Gas shell be conduct by customer request.

6 INFRARED REFLOW CONDITION

6.1. Lead-free Process



(reflow 2 cycles)

7 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test or Examination	Test Group									
	1	2	3	4	5	6	7	8	9	10
	Test Sequence									
Examination of Product	1、3	1、8	1、7	1、6	1、4				1	
Low Level Contact Resistance		2、11	2、10	2、9	2、5				3	1、4
Insulation Resistance		3、10	3、9	3、8						
Dielectric Withstanding Voltage		4、9	4、8	4、7						
Temperature rise	2									
Durability		6								
Vibration										2
Shock (Mechanical)										3
Thermal Shock			5							
Humidity			6							
Temperature life				5						
Salt Spray					3					
Solder ability						1				
Contact Retention Force							1			
FPC Insertion/Withdrawal Force		5、7								
Fitting Nail /Housing Retention Force								1		
Resistance to Soldering Heat									2	
Sample Size	2	4	4	4	4	2	4	4	4	4

8 FPC Insertion/Withdrawal Force

NO. OF Ckt.	Insertion Force (Kgf, Max)			Withdrawal Force (Kgf, Min)		
	1st	6th	20th	1st	6th	20th
4~9	1.30	1.20	1.10	0.30	0.22	0.20
10~14	1.35	1.17	1.00	0.30	0.24	0.22
15~24	2.30	2.00	1.70	0.48	0.37	0.34
25~36	3.45	3.00	2.55	0.82	0.61	0.57
37~50	4.80	4.17	3.55	1.22	0.90	0.85